

FORCE 10™



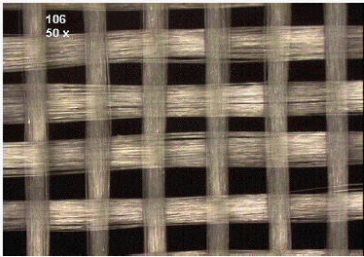
Channel Model and Material Characteristics

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Abstract: This technical presentation covers channel model changes and the resulting changes to material definitions.

- Channel SDD21 Limit line to change
- ICR Limit Line to change based on SDD21 Change
- Material Dk/Df to change based on SDD21 Change
- TX jitter to be reduced from 0.30UI to 0.28UI.
- DCD will not be added to the EIT Test.
- EIT value to be XXmv
- The simulations will be run with the latest channel models. In order to be consistent:
 - DCD at the TX 0.05
 - Transmit Jitter 0.28UI
 - Latest Package model
 - For the M20 channel NEXT2, NEXT6 and FEXT1 should be used.



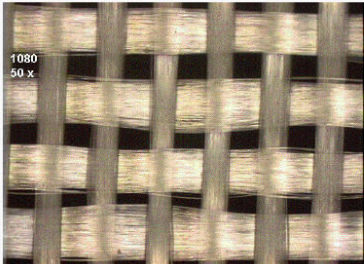
Glass Style: 106

Plain Weave
 Count: 56x56 (ends/in)
 Thickness: 0.0015 (in)

NOTE:

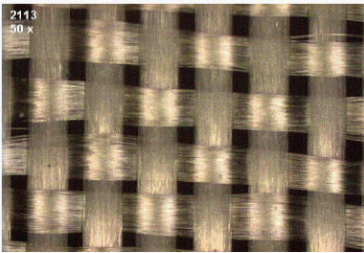
The plain weave yarn consists of yarns interlaced in an alternating fashion one over and one under every yarn.

Circuit board material is just multiple sheets of glass with copper traces and copper planes added for electrical connections.



Glass Style: 1080

Plain Weave
 Count: 60x47 (ends/in)
 Thickness: 0.0025 (in)

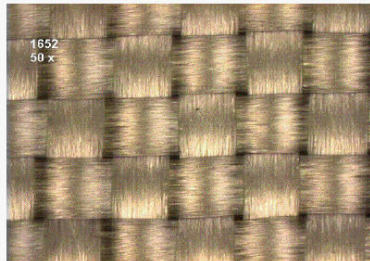


Glass Style: 2113

Plain Weave
 Count: 60x56 (ends/in)
 Thickness: 0.0029 (in)

NOTE:

The plain weave yarn consists of yarns interlaced in an alternating fashion one over and one under every yarn.

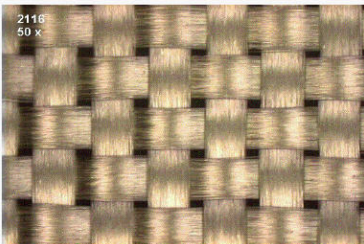


Glass Style: 1652

Plain Weave
 Count: 52x52 (ends/in)
 Thickness: 0.0045 (in)

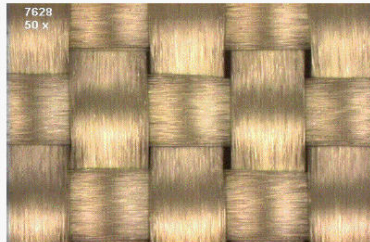
NOTE:

The plain weave yarn consists of yarns interlaced in an alternating fashion one over and one under every yarn.



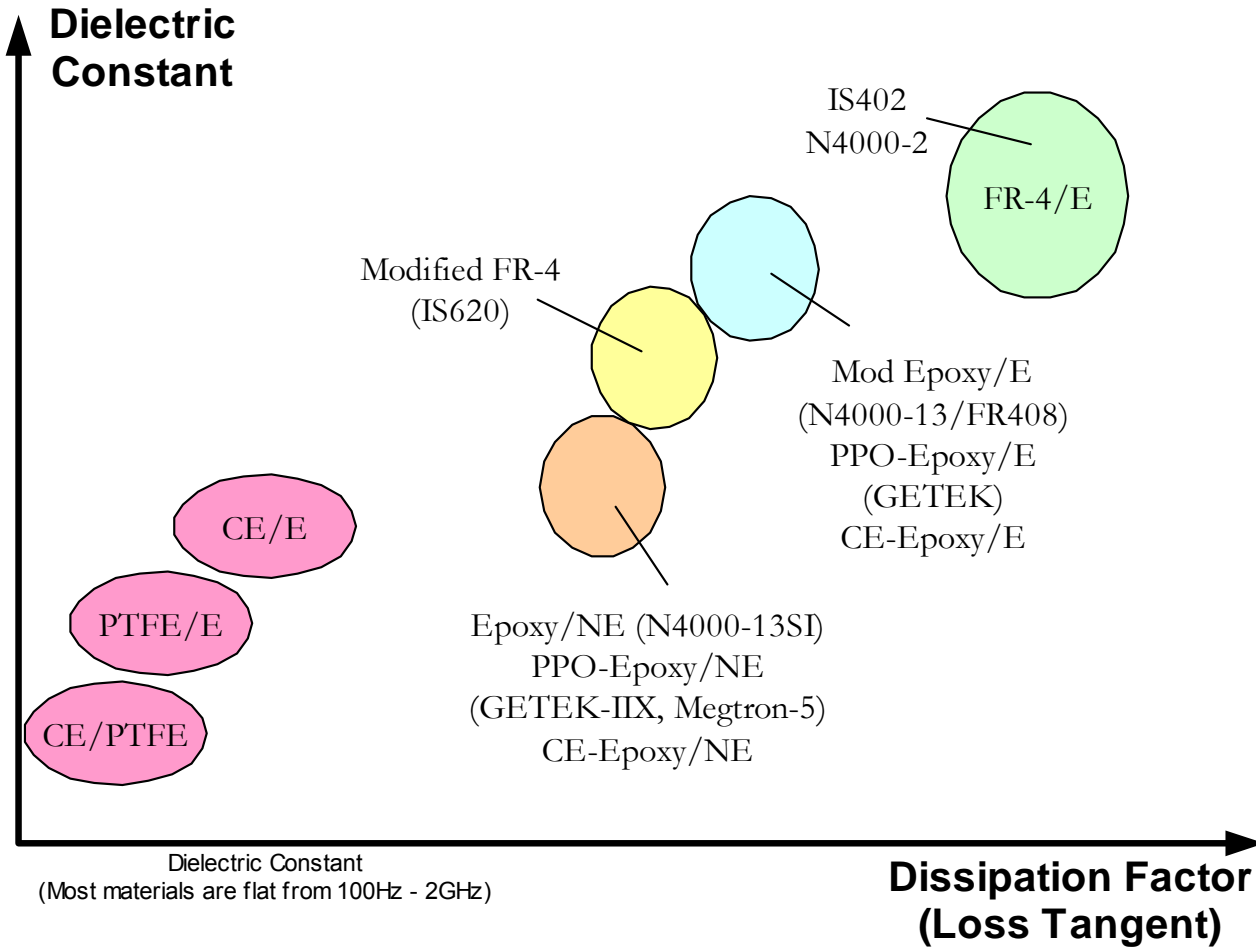
Glass Style: 2116

Plain Weave
 Count: 60x58 (ends/in)
 Thickness: 0.0038 (in)



Glass Style: 7628

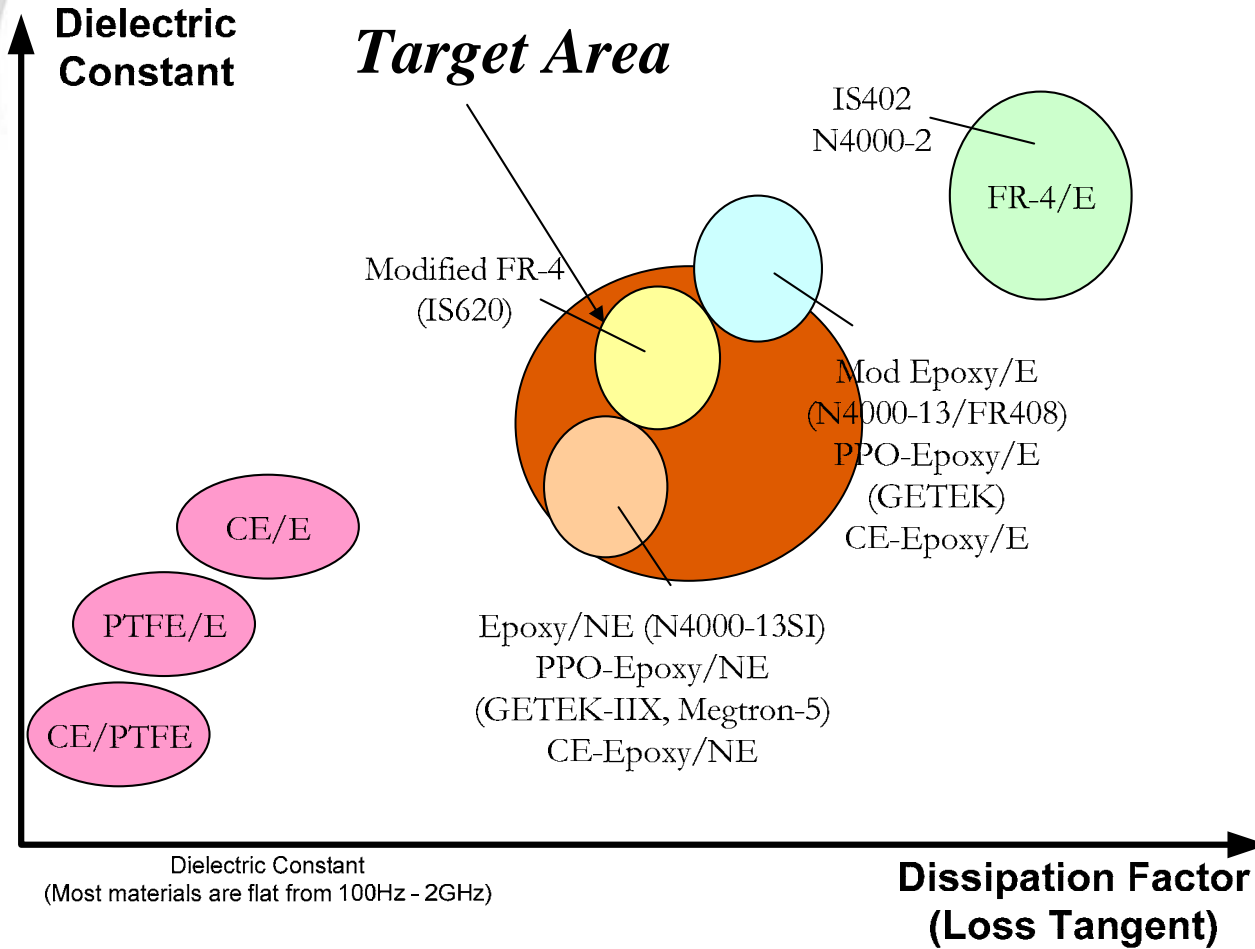
Plain Weave
 Count: 44x32 (ends/in)
 Thickness: 0.0068 (in)



Definition: “Improved FR-4” as defined by IEEE P802.3ap

- Improved FR-4 (Mid Resolution Signal Integrity):
 - 100Mhz: $Dk \leq 3.60$; $Df \leq .0092$
 - 1Ghz: $Dk \leq 3.60$; $Df \leq .0092$
 - 2Ghz: $Dk \leq 3.50$; $Df \leq .0115$
 - 5Ghz: $Dk \leq 3.50$; $Df \leq .0115$
 - 10Ghz: $Dk \leq 3.40$; $Df \leq .0125$
 - 20Ghz: $Dk \leq 3.20$; $Df \leq .0140$
- Temperature and Humidity Tolerance (0-55degC, 10-90% non-condensing):
 - $Dk: +/- .04$
 - $Df: +/- .001$
- Resin Tolerance (standard +/-2%):
 - $Dk: +/- .02$
 - $Df: +/- .0005$

Channel Model Perspective

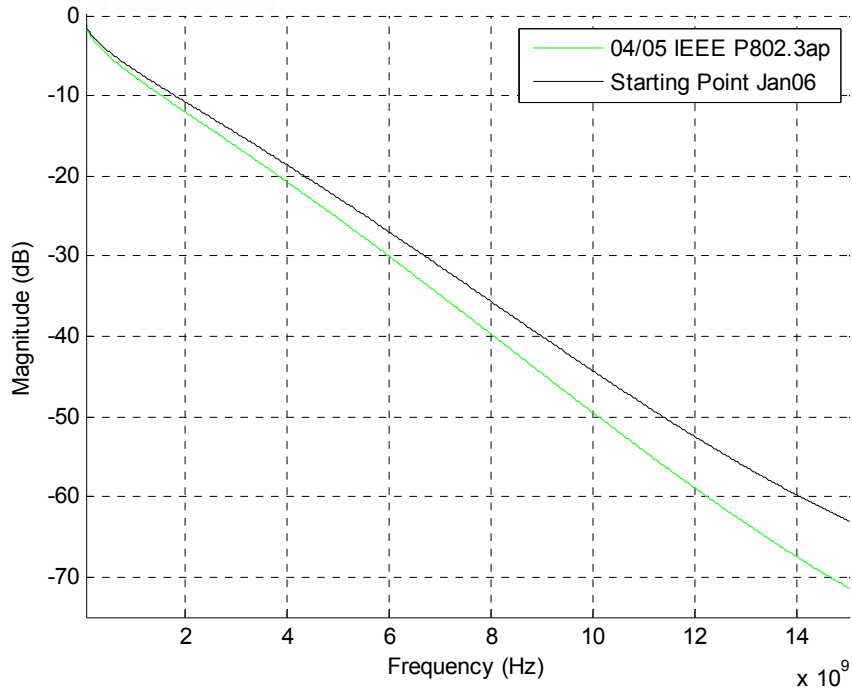


- Improved FR-4 (Mid Resolution Signal Integrity):
 - 100MHz: $Dk \leq 3.60$; $Df \leq .010$
 - 1Ghz: $Dk \leq 3.57$; $Df \leq .010$
 - 2Ghz: $Dk \leq 3.50$; $Df \leq .011$
 - 5Ghz: $Dk \leq 3.50$; $Df \leq .011$
 - 10Ghz: $Dk \leq 3.40$; $Df \leq .012$
 - 20Ghz: $Dk \leq 3.20$; $Df \leq .0125$
- Temperature and Humidity Tolerance (0-55degC, 10-90% non-condensing):
 - $Dk: +/- .04$
 - $Df: +/- .001$
- Resin Tolerance (standard +/-2%):
 - $Dk: +/- .02$
 - $Df: +/- .0005$

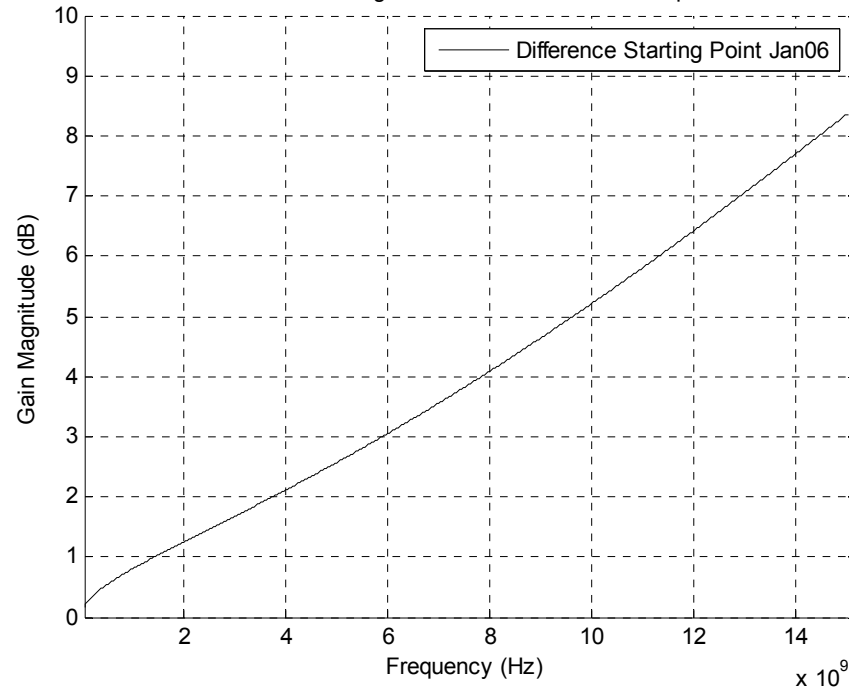
- $b1 = 2.00e-5$
- $b2 = 1.10e-10$
- $b3 = 3.20e-20$
- $b4 = -1.20e-30$
- $SDD21 = -20 \cdot \log_{10}(e) \cdot (b1 \cdot \sqrt{f} + b2 \cdot f + b3 \cdot f^2 + b4 \cdot f^3)$
- $f = 50\text{Mhz to } 15000\text{Mhz}$

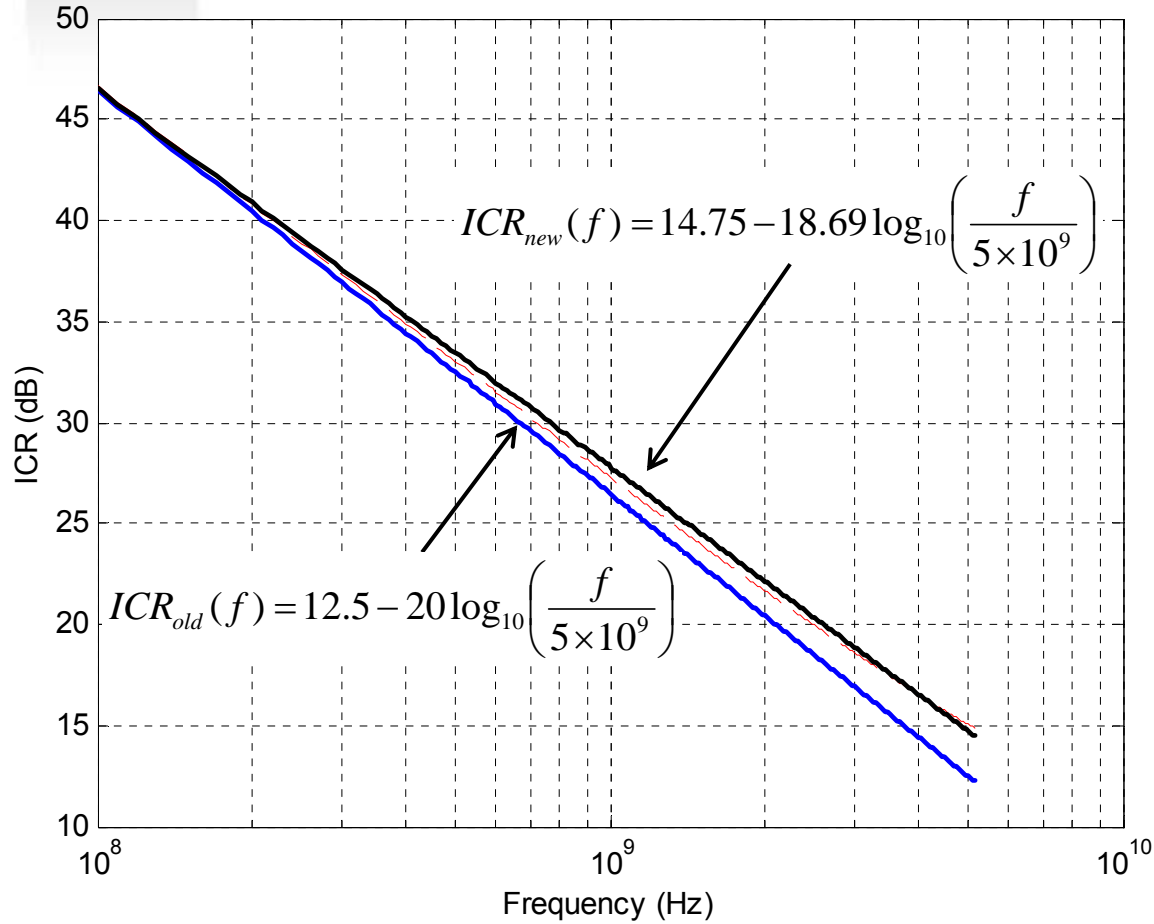
New Limit Line

OIF Jan06 SDD21 Mask



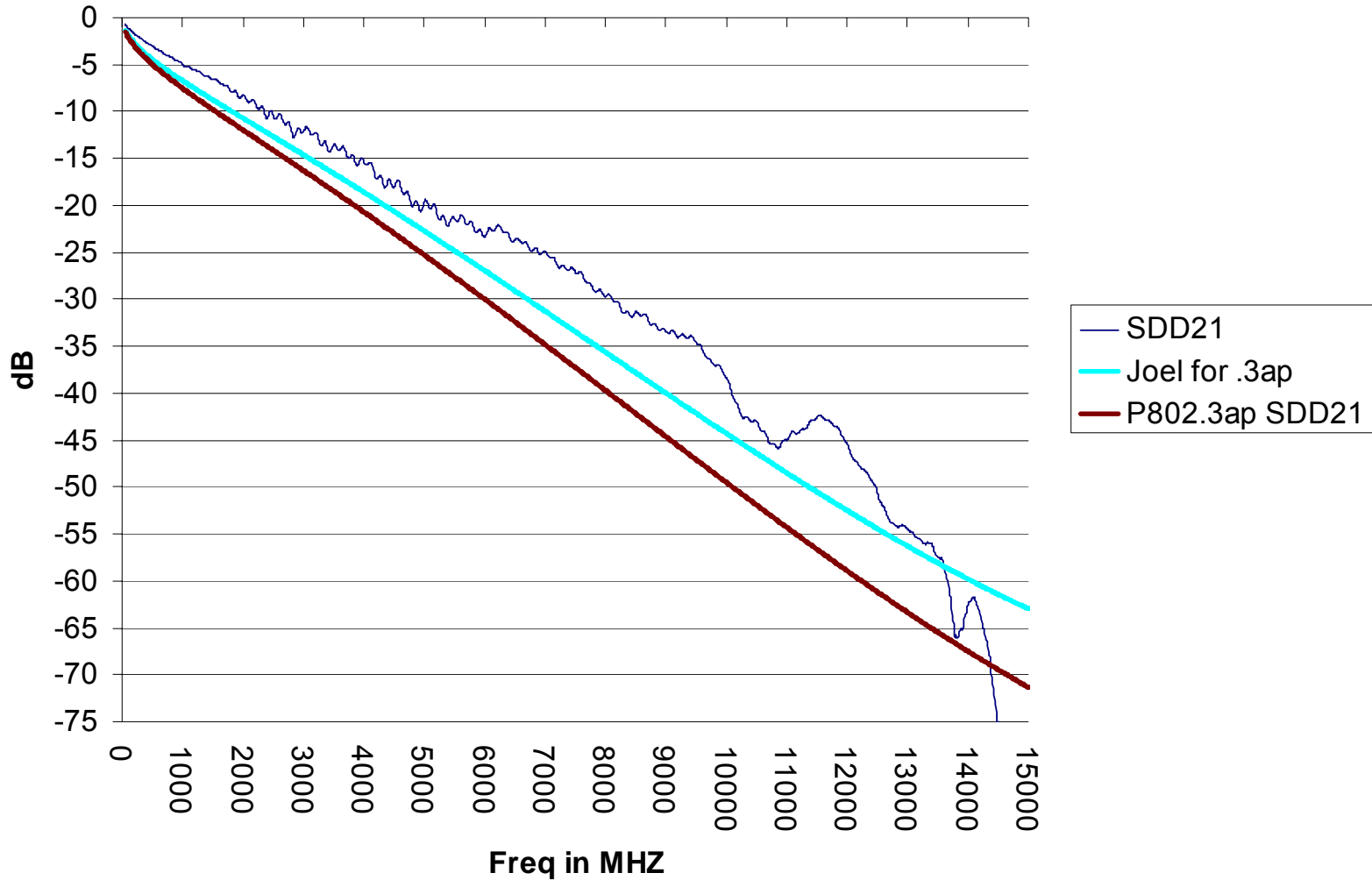
SDD21 Changes from 04/05 IEEE P802.3ap





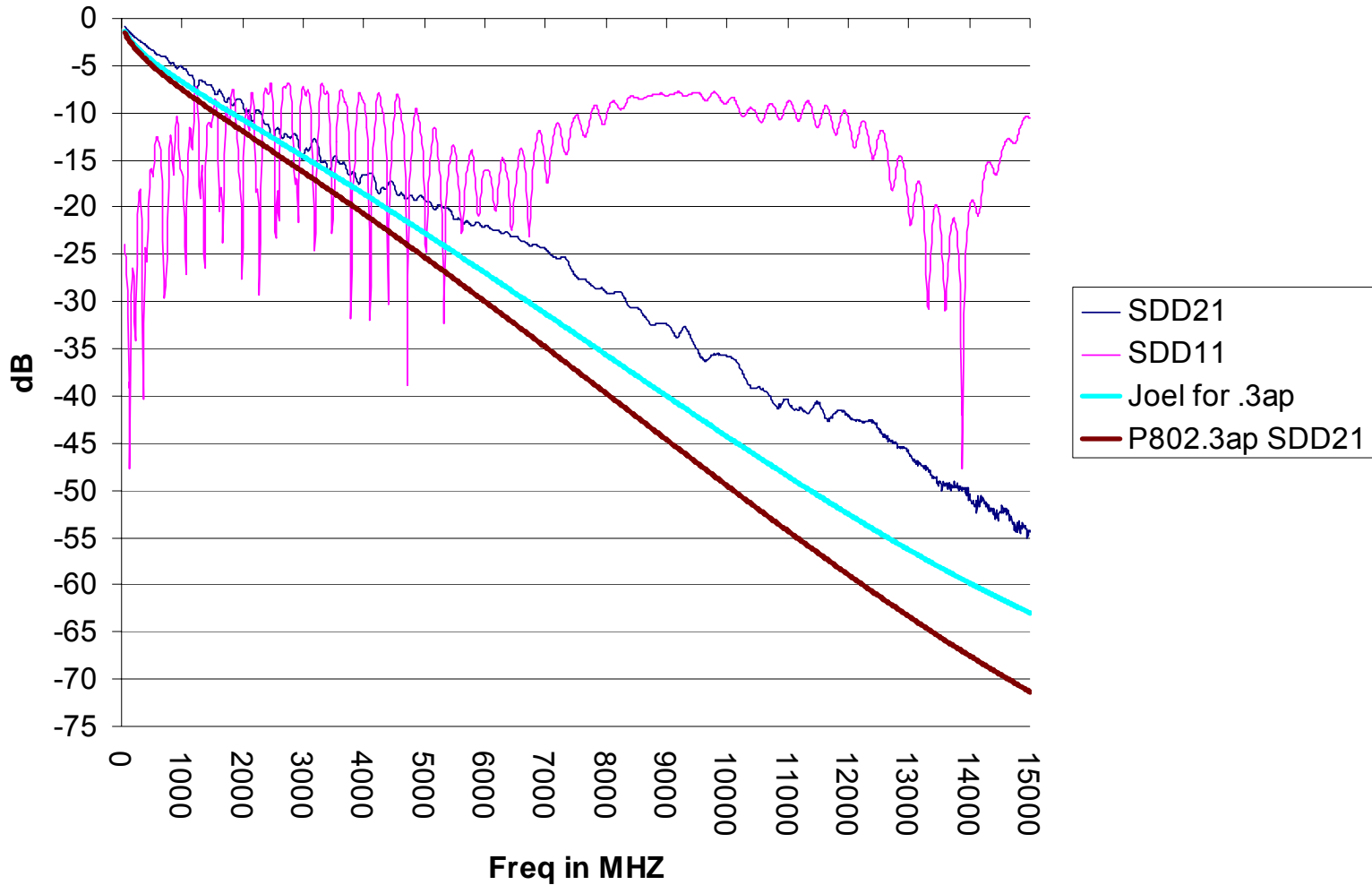
Black – new
Blue - old

SDD21 M20



Channel Model CH18_10_20_10

SDD21 SDD11 SDD22 CH18_10_20_10in N4000-13



Channel Model

CH20_5_5_20_10

SDD21 SDD11 SDD22 CH20_5_5_20_10in N4000-13

